COMPLIANT HALOGEN

**FREE** 



Vishay Siliconix

## **E Series Power MOSFET**

PRODUCT SUMMARY			
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700		
R <sub>DS(on)</sub> max. at 25 °C (Ω)	V <sub>GS</sub> = 10 V	0.9	
Q <sub>g</sub> max. (nC)	34		
Q <sub>gs</sub> (nC)	4		
Q <sub>gd</sub> (nC)	8		
Configuration	Single		

# DPAK (TO-252) G N-Channel MOSFET

#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION		
Package	DPAK (TO-252)	
Lead (Pb)-free and Halogen-free	SiHD6N62E-GE3	

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V <sub>DS</sub>	620	V
Gate-Source Voltage			$V_{GS}$	± 30	v
Continuous Drain Current (T. 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C		6	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	VGS at 10 V	$T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$	I <sub>D</sub>	4	Α
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	12	
Linear Derating Factor				0.63	W/°C
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	88	mJ
Maximum Power Dissipation			P <sub>D</sub>	78	W
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-Source Voltage Slope T <sub>J</sub> = 125 °C		dV/dt	37	1//	
Reverse Diode dV/dt d			12	- V/ns	
Soldering Recommendations (Peak Temperature) c for 10 s			300	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 2.5 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.6	G/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	620	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.76	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
		,	V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	$I_{GSS}$		V <sub>GS</sub> = ± 30 V	-	-	± 1	μA
			= 620 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3 A	-	0.78	0.90	Ω
Forward Transconductance	9fs	V <sub>DS</sub>	= 30 V, I <sub>D</sub> = 3 A	-	1.8	-	S
Dynamic		,					
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V,		-	578	-	
Output Capacitance	Coss		/ <sub>DS</sub> = 100 V,	-	36	-	1
Reverse Transfer Capacitance	C <sub>rss</sub>	1	f = 1 MHz		4	-	pF
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	.,		-	31	-	
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>	$V_{DS} = 0.0$	$V_{DS} = 0 \text{ V to } 496 \text{ V}, V_{GS} = 0 \text{ V}$		87	-	
Total Gate Charge	Qg			-	17	34	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V		-	4	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	1		-	8	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 496 V, I <sub>D</sub> = 3 A,		-	12	24	
Rise Time	t <sub>r</sub>			-	10	20	no
Turn-Off Delay Time	t <sub>d(off)</sub>	00	$V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		22	44	ns
Fall Time	t <sub>f</sub>			-	16	32	
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		-	1.3	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	7	
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	12	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 3 A, V <sub>GS</sub> = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 3 A, dl/dt = 100 A/μs, V <sub>R</sub> = 400 V		-	190	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	1.3	_	μC
Reverse Recovery Current	I <sub>RRM</sub>				11		A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

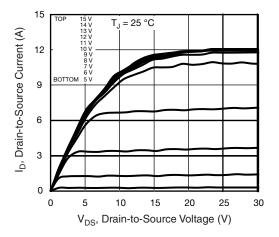


Fig. 1 - Typical Output Characteristics

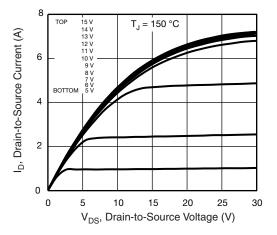


Fig. 2 - Typical Output Characteristics

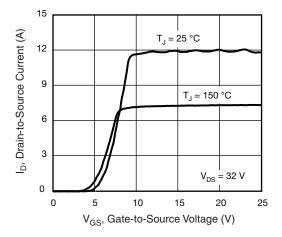


Fig. 3 - Typical Transfer Characteristics

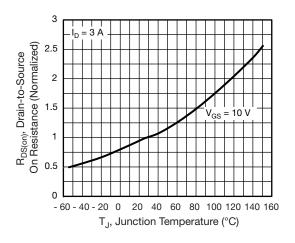


Fig. 4 - Normalized On-Resistance vs. Temperature

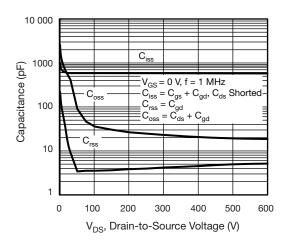


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

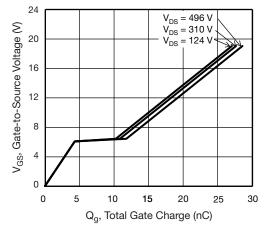


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



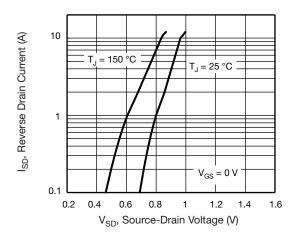


Fig. 7 - Typical Source-Drain Diode Forward Voltage

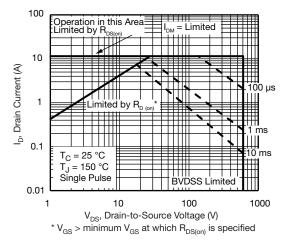


Fig. 8 - Maximum Safe Operating Area

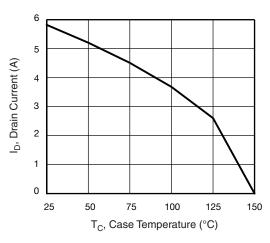


Fig. 9 - Maximum Drain Current vs. Case Temperature

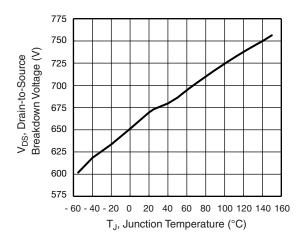


Fig. 10 - Temperature vs. Drain-to-Source Voltage

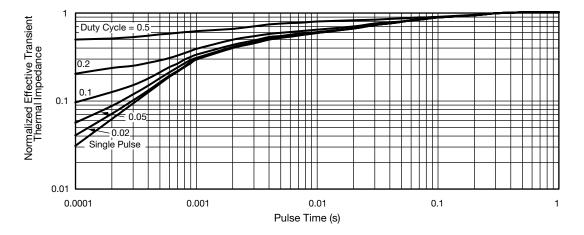


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

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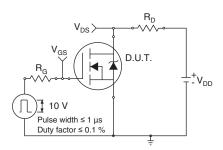


Fig. 12 - Switching Time Test Circuit

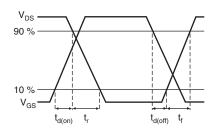


Fig. 13 - Switching Time Waveforms

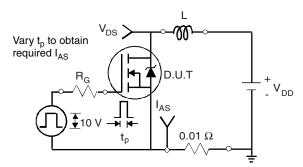


Fig. 14 - Unclamped Inductive Test Circuit

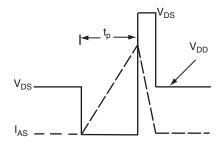


Fig. 15 - Unclamped Inductive Waveforms

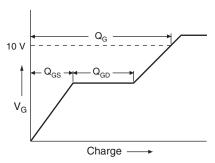


Fig. 16 - Basic Gate Charge Waveform

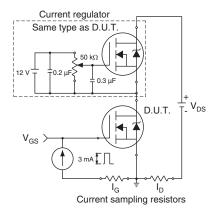
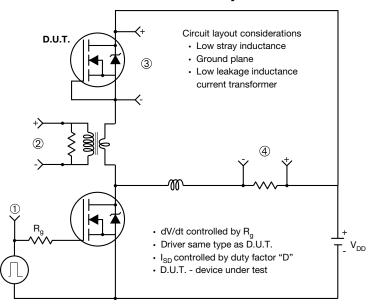


Fig. 17 - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



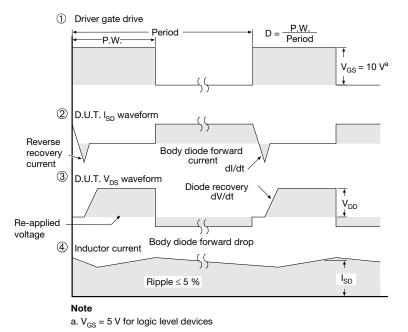


Fig. 18 - For N-Channel

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# **TO-252AA Case Outline**

#### **VERSION 1: FACILITY CODE = Y**







	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.38	
A1	-	0.127	
b	0.64	0.88	
b2	0.76	1.14	
b3	4.95	5.46	
С	0.46	0.61	
C2	0.46	0.89	
D	5.97	6.22	
D1	4.10	-	
Е	6.35	6.73	
E1	4.32	=	
Н	9.40	10.41	
е	2.28 BSC		
e1	4.56 BSC		
L	1.40	1.78	
L3	0.89	1.27	
L4	-	1.02	
L5	1.01	1.52	

#### Note

• Dimension L3 is for reference only



#### **VERSION 2: FACILITY CODE = N**



	MILLIMETERS		
DIM.	MIN.	MAX.	
Α	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	=	
Е	6.35	6.73	
E1	4.32 -		
е	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	ł ref.	
L2	0.51	BSC	
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

#### Notes

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022

DWG: 5347



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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